



Material Content Data Sheet



Sales Product Name		BTT6200-1ENA		Issued		14. September 2018			
MA#		MA002361656							
Package		PG-TDSO-8-31		Weight*		67.23 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.977	1.45	1.45	14527	14527	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141		
		non noble metal	zinc	7440-66-6	0.038	0.06		565	
		non noble metal	iron	7439-89-6	0.760	1.13		11301	
wire	non noble metal	non noble metal	copper	7440-50-8	30.851	45.88	47.08	458881	470888
		non noble metal	copper	7440-50-8	0.197	0.29	0.29	2929	2929
		encapsulation	organic material	carbon black	1333-86-4	0.098	0.15		1456
	plastics	epoxy resin	-	3.817	5.68		56775		
		inorganic material	silicondioxide	60676-86-0	28.709	42.70	48.53	427023	485254
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7396	7396	
plating	noble metal	silver	7440-22-4	0.825	1.23	1.23	12268	12268	
glue	plastics	epoxy resin	-	0.079	0.12		1179		
		noble metal	silver	7440-22-4	0.374	0.56	0.68	5559	6738
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com